

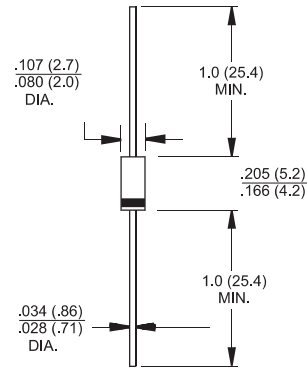


Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V0
- Ideally suited for use in very high frequency switching power supplies, inverters and as free wheeling diodes
- Glass passivated chip junction
- Excellent high temperature switching
- Ultrafast recovery time for high efficiency
- Soft recovery characteristics
- High temperature soldering guaranteed: 260°C/10 seconds/.375"(.95mm) lead lengths at 5 lbs., (2.3kg) tension
- Green compound with suffix "G" on packing code & prefix "G" on datecode.

Mechanical Data

- Case: JEDEC DO-204AL molded plastic body over passivated chip
- Terminals: Pure tin plated, lead free, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode
- Mounting Position: Any
- Weight: 0.012 ounce, 0.34 gram



Dimensions in inches and (millimeters)

Marking Diagram



UF1X = Specific Device Code
G = Green Compound
Y = Year
WW = Work Week

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.
Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%

Type Number	Symbol	UF1A	UF1B	UF1D	UF1G	UF1J	UF1K	UF1M	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current .375 (9.5mm) Lead Length @T _A = 55 °C	I _(AV)	1.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30							A
Maximum Instantaneous Forward Voltage @ 1.0A	V _F	1.0				1.7			V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =125 °C	I _R	5.0				150			uA
Maximum Reverse Recovery Time (Note 1)	T _{rr}	50				75			nS
Typical Junction Capacitance (Note 2)	C _j	17							pF
Typical Thermal Resistance (Note 3)	R _{θJA} R _{θJL}	60 15							°C/W
Operating/Storage Temperature Range	T _J , T _{STG}	-55 to + 150							°C

- Notes:
- Reverse Recovery Test Conditions: $I_F=0.5A$, $I_R=1.0A$, $I_{RR}=0.25A$
 - Measured at 1 MHz and Applied Reverse Voltage of 4.0 V D.C.
 - Thermal Resistance from junction to ambient and from Junction to Lead length .375" (9.5mm), Mounted on 0.2" x 0.2" (5mm x 5mm) Cu pads.

